

# Inductive Sensor with IO-Link

## I08H026

Part Number

weproTec



- Easy sensor configuration using the IO-Link interface
- Innovative ASIC circuit technology
- Integrated error display and error output
- Minimal mounting clearance thanks to wenglor weproTec

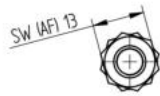
The Inductive Sensors have not only been equipped with ASIC, but rather with an IO-Link interface as well for ideal integration into networks. As a result, a total of three switching distances and two switching frequencies can be selected, and PNP/NPN as well as NO/NC/antivalent options can be set as desired. This reduces the number of variants while simultaneously expanding the scope of functions.


### Technical Data

Inductive Data	
Switching Distance	6 mm
Standard Target	18 × 18 mm
Correction Factors Stainless Steel V2A/CuZn/Al	1,01/0,59/0,55
Mounting	non-flush
Mounting A/B/C/D in mm	8/25/18/12
Mounting B1 in mm	0...7
Switching Hysteresis	< 10 %
Electrical Data	
Supply Voltage	10...30 V DC
Supply Voltage with IO-Link	18...30 V DC
Current Consumption (U <sub>b</sub> = 24 V)	< 11 mA
Switching Frequency	750 Hz
Temperature Drift	< 10 %
Temperature Range	-40...80 °C
Switching Output Voltage Drop	< 1 V
Switching Output/Switching Current	150 mA
Residual Current Switching Output	< 100 µA
Short Circuit Protection	yes
Reverse Polarity and Overload Protection	yes
Interface	IO-Link V1.1
Protection Class	III
Mechanical Data	
Housing Material	CuZn, nickel-plated
Degree of Protection	IP67
Connection	M12 × 1; 4-pin
Safety-relevant Data	
MTTFd (EN ISO 13849-1)	3706,54 a
Function	
Error Indicator	yes
Programmable switching distance	4/5/6 mm
Programmable switching frequency	yes
IO-Link	●
Switchable to NC/NO	●
Configurable as PNP/NPN/Push-Pull	●
Error Output	●
Connection Diagram No.	704
Suitable Connection Equipment No.	2
Suitable Mounting Technology No.	200   203

### Complementary Products

IO-Link Master  
Software



Legend		PT		Platinum measuring resistor		ENAR5422		Encoder A/Ā (TTL)	
+	Supply Voltage +	nc	not connected			ENB5422	Encoder B/B̄ (TTL)		
–	Supply Voltage 0 V	U	Test Input			ENa	Encoder A		
~	Supply Voltage (AC Voltage)	Ū	Test Input inverted			ENb	Encoder B		
A	Switching Output (NO)	W	Trigger Input			AMIN	Digital output MIN		
Ā	Switching Output (NC)	W–	Ground for the Trigger Input			AMAX	Digital output MAX		
V	Contamination/Error Output (NO)	O	Analog Output			AOK	Digital output OK		
Ṽ	Contamination/Error Output (NC)	O–	Ground for the Analog Output			SY In	Synchronization In		
E	Input (analog or digital)	BZ	Block Discharge			SY OUT	Synchronization OUT		
T	Teach Input	AMV	Valve Output			OLT	Brightness output		
Z	Time Delay (activation)	a	Valve Control Output +			M	Maintenance		
S	Shielding	b	Valve Control Output 0 V			rsv	reserved		
RxD	Interface Receive Path	SY	Synchronization			Wire Colors according to DIN IEC 757			
TxD	Interface Send Path	SY–	Ground for the Synchronization			BK	Black		
RDY	Ready	E+	Receiver-Line			BN	Brown		
GND	Ground	S+	Emitter-Line			RD	Red		
CL	Clock	⚡	Grounding			OG	Orange		
E/A	Output/Input programmable	SnR	Switching Distance Reduction			YE	Yellow		
	IO-Link	Rx+/-	Ethernet Receive Path			GN	Green		
PoE	Power over Ethernet	Tx+/-	Ethernet Send Path			BU	Blue		
IN	Safety Input	Bus	Interfaces-Bus A(+)/B(-)			VT	Violet		
QSD	Safety Output	La	Emitted Light disengageable			GY	Grey		
Signal	Signal Output	Mag	Magnet activation			WH	White		
Bi-D+/-	Ethernet Gigabit bidirect. data line (A-D)	RES	Input confirmation			PK	Pink		
EN05422	Encoder 0-pulse 0-0̄ (TTL)	EDM	Contactor Monitoring			GNYE	Green/Yellow		

The image contains three technical diagrams illustrating different types of vias in a multi-layer printed circuit board (PCB):

- Top Diagram:** Shows a cross-section of a multi-layer PCB with a microvia. The microvia is a small hole drilled into the top layer, with its depth labeled 'A'. The diameter of the microvia is labeled 'B'. The diameter of the microvia opening is labeled 'C'. The diameter of the microvia annular ring is labeled 'D'.
- Bottom Left Diagram:** Shows a cross-section of a multi-layer PCB with a through-hole via. The diameter of the through-hole via is labeled '1,5 x Sn'.
- Bottom Right Diagram:** Shows a cross-section of a multi-layer PCB with a buried via. The diameter of the buried via is labeled 'B1'.